

IN THE CLAIMS

1. (Currently amended) A method of reducing electromagnetic emissions from an electronic circuit, said electronic circuit comprising at least one electrical component and at least one grounding point that are disposed on an upper surface of a printed circuit board, said method comprising:

applying a non-conductive coating over said electrical component; and

applying a conductive coating over said non-conductive coating and in contact with said grounding point so as to ground said conductive coating and thereby reduce electromagnetic emissions from said electronic circuit.

2. (Previously presented) The method of claim 1, further comprising, prior to applying the conductive coating, opening a hole in the non-conductive coating above the at least one grounding point to enable contact between the conductive coating and the at least one grounding point.

3. (Previously presented) The method of claim 1, wherein applying the non-conductive coating comprises applying the non-conductive coating on a central portion of the electronic circuit where the at least one electrical component is disposed but not on an edge portion of the electronic circuit where the at least one grounding point is disposed; and

wherein applying the conductive coating comprises applying the conductive coating on the central portion of the electronic circuit to contact the non-conductive coating and applying the conductive coating on the edge portion of the electronic circuit to contact the at least one grounding point.

4. (Previously presented) The method of claim 1, wherein applying the non-conductive coating comprises conforming the non-conductive coating to a top surface of the at least one electrical component, and wherein applying the conductive coating comprises conforming the conductive coating to a top surface of the non-conductive coating and to a top surface of the grounding point.

5. (Currently amended) An electronic circuit comprising:
a printed circuit board;
circuit traces disposed on a surface of the printed circuit board;
at least one an electrical component mounted on the surface of the printed circuit board, the electrical component electrically connected to a circuit trace by a conductive element;
at least one a grounding pad disposed along a perimeter of the printed circuit board;
a non-conductive coating disposed over the ~~at least one~~ electrical component, the non-conductive coating conforming to a profile of the electrical component and having a substantially uniform thickness; and
a conductive coating disposed on the non-conductive coating and on the ~~at least one~~ grounding pad, the conductive coating contiguous with at least a portion of the ~~at least one~~ grounding pad.
6. (Currently amended) The electronic circuit of claim 5, the non-conductive coating having an opening disposed above the portion of the ~~at least one~~ grounding pad, the conductive coating physically touching the portion of the ~~at least one~~ grounding pad through the opening.
7. (Previously presented) The electronic circuit of claim 5, the electronic circuit having a central region and a peripheral region, a boundary between the central region and the peripheral region defined by an outermost edge of the non-conductive coating, the at least one grounding pad disposed at least partially within the peripheral region.
8. (Currently amended) The electronic circuit of claim 5, ~~the non-conductive coating conforming to an upper surface of the at least one electrical component;~~ the conductive coating conforming to ~~an upper surface~~ a profile of the non-conductive coating and ~~an upper surface~~ a profile of the ~~at least one~~ grounding pad.

9. (Previously presented) The electronic circuit of claim 8, wherein the non-conductive coating comprises a material selected from the group consisting of insulating tape, rubber, silicone, room-temperature vulcanizing silicone rubber, insulating varnish, and combinations thereof.
10. (Previously presented) The electronic circuit of claim 8, wherein the conductive coating comprises a material selected from the group consisting of conductive paint, silver paint, and combinations thereof.
11. (Cancelled)
12. (Currently amended) The electronic circuit of claim 7, the ~~at least one~~ grounding pad disposed entirely within the peripheral region.
13. (Previously presented) The method of claim 1, wherein applying the non-conductive coating over the electrical component comprises applying the non-conductive coating to a top surface of the electrical component, wherein applying the conductive coating over the non-conductive coating and in contact with the grounding point comprises applying the conductive coating to a top surface of the non-conductive coating and to a top surface of the grounding point, and wherein applying the conductive coating occurs after applying the non-conductive coating.
14. (Currently amended) The method of claim 1, wherein applying the non-conductive coating comprises applying the non-conductive coating such that the non-conductive coating exposes at least a portion of an upper surface of the ~~at least one~~ grounding point.
15. (Currently amended) The method of claim 1, wherein applying the conductive coating comprises applying the conductive coating such that the conductive coating is contiguous with at least a portion of the ~~at least one~~ grounding point.

16. (Currently amended) A device comprising:
a circuit board having a peripheral region and a central region;
electrical components disposed within the central region of the circuit board;
~~at least one~~ a grounding pad disposed within the peripheral region of the circuit board;
a non-conductive coating disposed on at least one of the electrical components,
the non-conductive coating having a substantially uniform thickness; and
a conductive coating disposed on the non-conductive coating and disposed on the at least one grounding pad, the conductive coating contiguous with at least a first portion of an upper surface of the ~~at least one~~ grounding pad, the conductive coating conforming to a profile of the electrical components.
17. (Previously presented) The device of claim 16, wherein the peripheral region surrounds the central region.
18. (Currently amended) The device of claim 17, wherein the non-conductive coating is contiguous with a second portion of the upper surface of the ~~at least one~~ grounding pad, the first portion and the second portion constituting an entirety of the upper surface of the ~~at least one~~ grounding pad.
19. (Previously presented) The device of claim 17, wherein the non-conductive coating is disposed on a first portion of the central region, the first portion less than an entirety of the central region.